



QTH-030-01-L-D-A

QTH SERIES

HIGH SPEED GROUND PLANE HEADER

UL
FILE NO. E111594

CSA
FILE NO. 090871 0 00

28+
Gbps

QTH	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	—030, —060, —090 (60 total pins per bank = —D) —020, —040, —060 (20 pairs per bank = —D—DP)	Specify LEAD STYLE from chart	—F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails —L = 10μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails —C* = Electro-Polished Selective 50μ" (1.27 μm) min Au over 150μ" (3.81 μm) Ni on Signal Pins in contact area, 10μ" (0.25 μm) min Au over 50μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50μ" (1.27 μm) min Ni on all solder tails	—D = Single-Ended —D—DP = Differential Pair (—01 only)		—K = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad (N/A with —05 & —07 lead style) —TR = Tape & Reel (—090 positions maximum) —L = Latching Option (—01 lead style only) (N/A on —060 (—D—DP) & —090)

$-D = (\text{No. of Pins per Row}/30) \times (20.00) .7875$
 $-DP = (\text{No. of Pairs per Row}/20) \times (20.00) .7875$

(20.00) .7875
 (7.11) .280
 .01
 .02
 (0.50) .0197
 (0.20) .008
 A
 —01 & —02
 —03 thru —09

QTH LEAD STYLE	A	HEIGHT WITH QSH*
—01	(4.27) .168	(5.00) .197
—02	(7.26) .286	(8.00) .315
—03	(10.27) .404	(11.00) .433
—04	(15.25) .600	(16.00) .630
—05	(18.26) .718	(19.00) .748
—07	(24.24) .954	(25.00) .984
—09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height.

- Board Spacing Standoffs. See SO Series.